

an interconnecting medium contained within said package, wherein said [probe membrane] interconnecting medium has electrical paths adaptable for coupling to test circuitry, said medium including a medium surface, said medium surface having a plurality of probe tips affixed thereto, a plurality of standoffs affixed thereto, and a lower surface, wherein said probe tips are adaptable for making electrical contact with pads on said semiconductor device and are compliant bump probe tips;

a bonding layer comprising an elastomeric material interposed between said package lid lower surface and said semiconductor device upper surface; and

a bond layer comprising an elastomeric material interposed between said interconnecting medium lower surface and said package base upper surface, said package base being adapted for receiving said interconnecting medium.

REMARKS

Claim 30 has been amended to correct an obvious error in view of the change of terminology from the claim from which this claim was originally copied in view of the discussion thereof. All claims are retained in otherwise unamended condition.

Please treat the Declaration filed November 15, 2001, stated to be under 37 C.F.R. 1.131, to be both under 37 C.F.R. 1.608(b) as well as under 37 C.F.R. 1.131 for reasons which will become evident from the arguments presented hereinbelow. It is believed that the Declaration filed November 15, 2001 should have been so treated ab initio. The Declaration filed November 15, 2001 and signed by the inventors clearly establishes evidence which demonstrates that applicants are prima facie entitled to a judgment relative to the patentee. The Declaration and attached evidence which predates the filing